

## Special Issue

# MEMS Sensors: Past, Present and Future

### Message from the Guest Editors

Alongside the rapid development of sensing and manufacturing technologies, numerous novel MEMS sensors have emerged with a broad range of applications. These sensors include accelerometers, gyroscopes, hydrophones, pressure sensors, strain gauges, flow sensors, gas sensors, thermometers, and sensors for special applications, such as ultra-high-precision sensors for geophysical applications and sensors working under extreme conditions of shock, temperature, humidity, and chemical exposure. Their performances are determined by sensing mechanisms, structural design, fabrication techniques, detecting circuits and working environments, etc., and can be optimized by means of theoretical analysis, simulation, and calibration. This Special Issue seeks to showcase research papers and review articles discussing novel sensing mechanisms, design, fabrication, detecting circuits, calibration methods, and applications of MEMS sensors. Areas of interest include, but are not limited to:

- Sensing mechanisms
- Structural design
- System modeling and simulation
- Advanced fabrication techniques
- Detecting circuits
- Reliability of sensors
- Calibration methods
- New applications

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### Deadline for manuscript submissions

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